

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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FFPF10UP30ST Ultrafast Recovery Power Rectifier

Features

• Ultrafast with Soft Recovery : < 45ns

• High Reverse Voltage : V_{RRM} = 300V

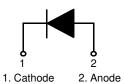
· Avalanche Energy Rated

· Planar Construction

Applications

- · General purpose
- · Switching Mode Power Supply
- · Free-wheeling diode for motor application
- Power switching circuits





Absolute Maximum Ratings (per diode) T_a = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V_{RRM}	Peak Repetitive Reverse Voltage	300	V
V_{RWM}	Working Peak Reverse Voltage	300	V
V _R	DC Blocking Voltage	300	V
I _{F(AV)}	Average Rectified Forward Current @ T _C = 125°C	10	А
I _{FSM}	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	100	A
$T_{J,}T_{STG}$	Operating Junction and Storage Temperature	- 65 to +150	°C

Thermal Characteristics T_a = 25°C unless otherwise noted

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	4.0	°C/W

$\textbf{Electrical Characteristics} \quad \text{(per diode)} \quad \textbf{T}_a = 25^{\circ} \textbf{C} \text{ unless otherwise noted}$

Symbol	Parameter		Min.	Тур.	Max.	Units
V _{FM} *	I _F = 10A I _F = 10A	T _C = 25 °C T _C = 150 °C	-	-	1.4 1.2	V V
I _{RM} *	V _R = 300V V _R = 300V	T _C = 25 °C T _C = 150 °C	-	-	100 500	μ Α μ Α
t _{rr}	I_F =1A, di/dt = 100A/ μ s, V_{CC} = 30V I_F =10A, di/dt = 200A/ μ s, V_{CC} = 195V	$T_C = 25 ^{\circ}C$ $T_C = 25 ^{\circ}C$	-	-	35 45	ns ns
t _a t _b Q _{rr}	$I_F = 10A$, di/dt = 200A/ μ s, $V_{CC} = 195V$	$T_C = 25 ^{\circ}C$ $T_C = 25 ^{\circ}C$ $T_C = 25 ^{\circ}C$		11 13 20		ns ns nC
W _{AVL}	Avalanche Energy (L = 20mH)		20	-	-	mJ

^{*} Pulse Test: Pulse Width=300 μ s, Duty Cycle=2%

Typical Performance Characteristics

Figure 1. Typical Forward Voltage Drop

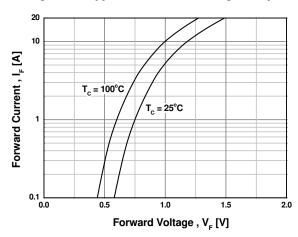


Figure 2. Typical Reverse Current

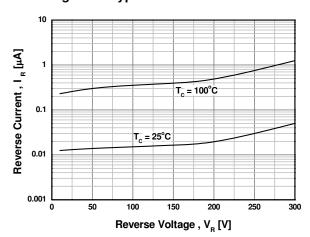


Figure 3. Typical Junction Capacitance

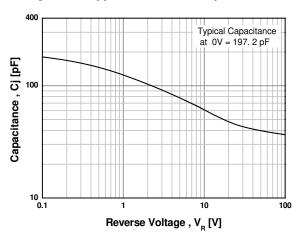


Figure 4. Typical Reverse Recovery Time

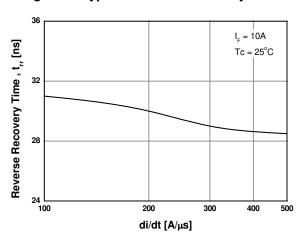


Figure 5. Typical Reverse Recovery Current

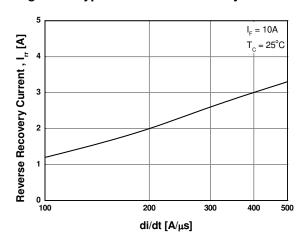
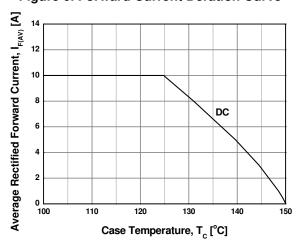
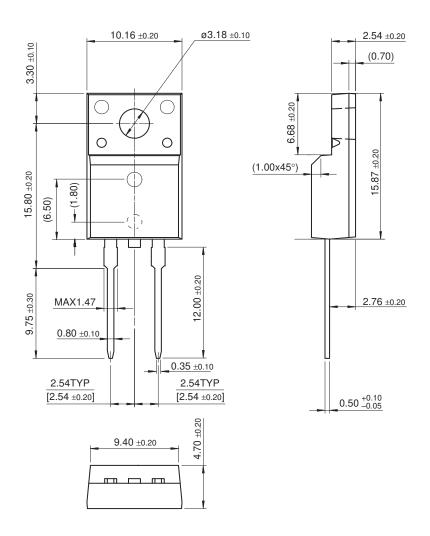


Figure 6. Forward Current Deration Curve



Package Demensions

TO-220F 2L



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